

RELIABILITY REPORT





Reliability Data Report Product Family R553

LT2940 / LT4275

Reliability Data Report

Report Number: R553

Report generated on: Thu Dec 21 15:30:33 PST 2017

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES ^{2,3}
QFN/DFN	77	1213	1213	222	0
SOIC/MSOP	77	1025	1025	77	0
Totals	154	-	-	299	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	48	1508	1508	1	0
SOIC/MSOP	50	1401	1401	1	0
Totals	98	-	-	2	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	45	1508	1508	4	0
SOIC/MSOP	50	1401	1401	5	0
Totals	95	-	-	9	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	42	1508	1508	4	0
SOIC/MSOP	50	1401	1401	5	0
Totals	92	-	-	9	0

(1) Assumes Activation Energy = 1.0 Electron Volts
 (2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =6.13 FITS
 (3) Mean Time Between Failure in Years = 18619.06
 Note: 1 FIT = 1 Failure in One Billion Hours.
 Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL1 Preconditioning